

### **REMARKS**

Claims 1 to 20 remain in the present application. Claims 5, 7, 11 and 14 have been amended for which there is support in the specification, claims and drawings as originally filed.

Reconsideration of the Examiner's decisions and reexamination of this application are respectfully requested.

#### **The §112 rejections:**

I. Claims 1 to 20 have been rejected by the Examiner under 35 USC §112, first paragraph. According to the Examiner, the claims have been rejected "because the specification, while being enabling for a seed layer (or seed layer of TiN with a cubic structure) that control the crystal structure of the main layer (or the TaN main layer) as described in [para 16] and [para 17], does not reasonably provide enablement for 'second crystal structure is controlled by the first crystal structure' as recited in claims 1 and 14." The Examiner goes on to state that "Nowhere to find such 'crystal structure is controlled by other such crystal structure' or any indication that the such 'cubic structure' (as noted in [para 17]) is in fact a 'crystal structure.'".

This rejection is without merit. Paragraph 17 clearly states that "a thin seed layer of TiN is put down first with a cubic structure to control the crystal structure of the main layer [i.e., the TaN]." That is, the crystal structure of the second material (i.e, the TaN) is controlled by the crystal structure of the first material (i.e, the TiN). The Examiner also appears to be saying that there is no indication that the "cubic structure" referenced numerous times in the specification is a crystal structure. This is incorrect. It is basic material science that a cubic structure is a type of crystal structure. For the Examiner's

edification, attached to this amendment is a page from the Metals Handbook clearly showing that a cubic structure is a crystal structure.

Withdrawal of this rejection is respectfully requested.

**II.** Claims 1 to 20 have been rejected by the Examiner under 35 USC 112, second paragraph, as being indefinite.

As to claims 1, 11 and 14, these claims are allegedly indefinite for reciting “said second crystal structure is controlled by the first crystal structure” since there is no cooperative relationship between the two,

According to the teaching of the invention, when you deposit the second material (e.g., TaN) on the first material (e.g., TiN), the second material takes on the crystal structure of the first material. This is not true for all materials but it is true for the materials claimed by Applicants. There are no missing elements. The rejection of claims 1, 11 and 14 is erroneous and should be withdrawn.

As to claim 5, there are allegedly insufficient antecedent basis for “said TiN” and “said TaN”.

This rejection is well placed and Applicants have amended claim 5 to provide the antecedent basis.

As to claim 7, there is allegedly insufficient antecedent basis for “said TaN”.

This rejection is well placed and Applicants have amended claim 7 to provide the antecedent basis.

As to claim 11, the recitation of “rho” allegedly renders the claim indefinite.

Claim 11 has been amended to substitute “resistivity” for “rho”.

As to claim 14, there is allegedly insufficient antecedent basis for “said first resistive material” and the recitation of “TCR” allegedly renders the claim indefinite.

Claim 14 has been amended to provide antecedent basis for “said first resistive material” and “TCR” has been spelled out.

In view of the above remarks, the rejection of claims 1 to 20 under 35 USC §112, second paragraph, should now be moot.

The §102 rejections:

Claims 1 and 14 have been rejected by the Examiner under 35 USC §102(b) as being anticipated by Holmes U.S. Patent 3,896,284.

Holmes merely discloses a bilayer resistor. The first layer is typically chromium and the second layer is typically tantalum. There is no disclosure in Holmes, whether explicitly or inherently, that “said second crystal structure is controlled by said first crystal structure” as claimed by Applicants. The materials used by Holmes (chromium or nichrome and tantalum) are different than those used by Applicants. Moreover, there is no basis in Holmes for the Examiner’s statement “wherein the sheet resistivity and temperature coefficient of resistance of the second layer 12 is effectively ‘controlled’ or ‘realized’ by the thickness and cubic structure of the first layer” since there appears to be no disclosure at all in Holmes pertaining to the crystal structure of the first layer. Most importantly, notwithstanding the foregoing erroneous statement by the Examiner, there is no showing by the Examiner where “said second crystal structure is controlled by said first crystal structure” as claimed by Applicants can be found in Holmes.

For anticipation, every element of the claim must be shown in the reference. Since Holmes does not disclose “said second crystal structure is controlled by said first crystal structure” as claimed by Applicants, Holmes cannot anticipate Applicants’ claims 1 and 14.

The §103 rejections:

Claims 4, 11 and 18 have been rejected by the Examiner under 35 USC 103(a) as being unpatentable over Holmes in view of admitted prior art in [para 70] of Applicants’ specification.

Inasmuch as claim 4 depends from claim 1, and claim 1 is believed to be patentable, then claim 4 should be patentable as well. No independent ground of patentability is asserted for claim 4 at this time.

Claim 11 is patentable because the Examiner has failed to state a *prima facie* case of obviousness with respect to claim 11. As a matter of fact, the Examiner has failed to provide any rationale whatsoever for the rejection of claim 11. The Examiner has failed to provide any rationale why Holmes renders Applicants’ claim 11 obvious and certainly has provided no rationale why Holmes teaches “said second crystal structure is controlled by said first crystal structure” as claimed by Applicants.

Claim 18 claims an embodiment wherein there is a third resistor type which comprises “a single layer of said second resistive material”. The Examiner has failed to state a *prima facie* case of obviousness with respect to claim 18 in that the Examiner has failed to provide any rationale whatsoever for the rejection of claim 18. Holmes teaches two types of resistors, namely, a resistor of the first layer only and a resistor of the first and second layers. Holmes, however, fails to teach a resistor having the second layer only.

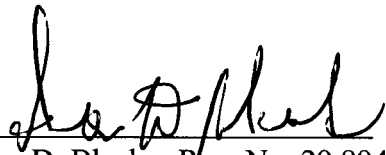
In view of the preceding remarks, claims 4, 11 and 18 are deemed to be patentable over the cited art.

**It is noted that the Examiner has only rejected claims 1 and 14 under 35 USC §102(b) and claims 4, 11 and 18 under 35 USC §103(a). Thus, claims 2, 3, 5 to 10, 12, 13 and 15 to 17 have not been rejected on prior art grounds. In view of the above remarks indicating the rejections of claims 1 to 20 under 35 USC §112 should be either withdrawn or are moot, claims 2, 3, 5 to 10, 12, 13 and 15 to 17 should be in condition for allowance.**

Summary:

In view of all of the preceding remarks, it is submitted that all of claims 1 to 20 are in condition for allowance. If the Examiner finds this application deficient in any respect, the Examiner is invited to telephone the undersigned at the Examiner's earliest convenience to resolve such deficiency.

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# METALS HANDBOOK



*Prepared under the direction of the*  
METALS HANDBOOK COMMITTEE

*Edited by*  
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*Published by*  
THE AMERICAN SOCIETY FOR METALS  
Metals Park  
Novelty, Ohio

*Copyrighted, 1948,*

BY THE

AMERICAN SOCIETY FOR METALS

Reprinted May 1952

Reprinted January 1954

Reprinted May 1956

Reprinted January 1958

Reprinted April 1960

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PRINTED IN THE UNITED STATES OF AMERICA



Coefficient of Linear Thermal Expansion near 20°C, micro-in./°C	Coefficient of Linear Thermal Expansion near 68°F, micro-in./°F	Thermal Conductivity near 20°C, cal/sq cm/cm per deg Cent/sec	Electrical Resistivity, microhm-cm	Modulus of Elasticity, 10 <sup>8</sup> psi	Crystal Structure	Lattice Constants at 20°C (68°F), kX-units†		c or Axial Angle or Temp	Closest Approach of Atoms	Element
						a	b			
(c) 23.9	(c) 13.3	0.53	2.655 (20°C)	10	Face-centered cubic	4.0408	.....	.....	2.856	Actinium
(b) (c) 8.5 to 10.8	(b) (c) 4.7 to 6.0	0.045	39.0 (0°C)	11.3	Rhombohedral	4.4974	.....	57° 6.5'	2.898	Aluminum
.....	.....	0.406 × 10 <sup>-4</sup>	.....	.....	Face-centered cubic	5.42	.....	(-233°C)	3.83	Americium
4.7	2.6	.....	35 (0°C)	.....	Rhombohedral*	4.151	.....	53° 49'	2.50	Antimony
.....	.....	.....	.....	.....	Body-centered cubic*	5.015	.....	.....	4.34	Arsenic
(1) 12.4	(1) 6.9	0.38	5.9 (0°C)	37	Close-packed hexagonal*	2.2810	.....	3.5771	2.221	Astatine
13.3	7.4	0.020	106.8 (0°C)	4.6	Rhombohedral	4.7361	.....	57° 14.2'	3.105	Barium
(c) 8.3	(c) 4.6	.....	1.8 × 10 <sup>12</sup> (0°C)	.....	Orthorhombic (?)	17.86	8.93	10.13	.....	Beryllium
.....	.....	.....	.....	.....	Orthorhombic	4.48	6.67	8.72 (-150°C)	2.27	Bismuth
29.8	16.6	0.22	6.83 (0°C)	8	Close-packed hexagonal	2.9727	.....	5.606	2.972	Boron
22	12	0.3	3.43 (0°C)	3	Face-centered cubic*	5.56	.....	.....	3.93	Bromine
(c) 0.6 to 4.3	(c) 0.3 to 2.4	0.057	1375 (0°C)	0.7	Hexagonal*	2.4564	.....	6.6906	1.42	Cadmium
.....	.....	.....	.....	.....	Face-centered cubic*	5.143	.....	.....	3.64	Calcium
97	54	.....	78 (20°C)	.....	Body-centered cubic	6.05	.....	(-173°C)	5.24	Carbon (graphite)
.....	.....	0.172 × 10 <sup>-4</sup>	18.83 (0°C)	.....	Tetragonal	8.56	.....	6.12 (-185°C)	1.81	Cerium
6.2	3.4	0.16	13 (28°C)	36	Body-centered cubic*	2.8787	.....	.....	2.493	Cesium
12.3	6.8	0.165	6.24 (20°C)	30	Close-packed hexagonal*	2.502	.....	4.061	2.501	Chlorine
7.1	4.0	.....	13.1 (18°C)	.....	Body-centered cubic	3.2941	.....	.....	2.853	Chromium
16.5	9.2	0.94	1.673 (20°C)	16	Face-centered cubic	3.6080	.....	.....	2.551	Cobalt
.....	.....	.....	.....	.....	Close-packed hexagonal	3.578	.....	5.648	3.499	Columbium
.....	.....	.....	.....	.....	Close-packed hexagonal*	3.532	.....	5.589	3.459	Copper
.....	.....	.....	.....	.....	Body-centered cubic	4.573	.....	.....	3.960	Curium
.....	.....	.....	.....	.....	Close-packed hexagonal	3.622	.....	5.748	3.554	Dysprosium
18	10	.....	53.4 (0°C)	.....	One-face-centered orthorhombic	4.517	4.511	7.645	2.437	Erbium
.....	.....	.....	89,000 (0°C)	.....	Diamond cubic	5.647	.....	.....	2.445	Europtium
14.2	7.9	0.71	2.19 (0°C)	12	Face-centered cubic	4.0701	.....	.....	2.878	Fluorine
.....	.....	3.32 × 10 <sup>-4</sup>	.....	.....	Close-packed hexagonal*	3.200	.....	5.077	3.14	Francium
.....	.....	4.06 × 10 <sup>-4</sup>	.....	.....	Close-packed hexagonal (?)	3.57	.....	5.83 (-271.5°C)	3.57	Gadolinium
.....	.....	.....	.....	.....	Close-packed hexagonal	3.557	.....	.....	3.480	Gallium
.....	.....	.....	.....	.....	Hexagonal	3.75	.....	6.12 (-271°C)	.....	Germanium
33	18	0.057	8.37 (0°C)	.....	Face-centered tetragonal	4.585	.....	4.941	3.24	Gold
93	52	10.4 × 10 <sup>-4</sup>	1.3 × 10 <sup>16</sup> (20°C)	.....	Orthorhombic	4.777	7.251	9.773	2.70	Hafnium
6.8	3.8	0.14	5.3 (20°C)	75	Face-centered cubic	3.8312	.....	.....	2.709	Helium
11.7	6.5	0.18	9.71 (30°C)	28.5	Body-centered cubic*	2.8606	.....	(-191°C)	2.476	Holmium
.....	.....	0.21 × 10 <sup>-4</sup>	.....	.....	Face-centered cubic	5.68	.....	.....	4.02	Hydrogen
(c) 29.3	(c) 16.3	0.083	59 (18°C)	.....	Close-packed hexagonal*	3.754	.....	6.063	3.73	Indium
56	31	0.17	8.55 (0°C)	2.6	Face-centered cubic	4.9395	.....	.....	3.493	Iodine
.....	.....	.....	.....	.....	Body-centered cubic	3.5019	.....	.....	3.033	Iridium
(c) 26	(c) 14	0.38	4.46 (20°C)	6.5	Close-packed hexagonal	3.509	.....	5.559	3.439	Iron
22	12	.....	185 (20°C)	23	Close-packed hexagonal	3.2028	.....	5.1998	3.190	Krypton
.....	.....	0.0201	94.1 (0°C)	.....	Cubic* (complex)	8.894	.....	.....	2.24	Lanthanum
(c) 4.9	(c) 2.7	0.35	5.17 (0°C)	50	Rhombohedral	2.999	.....	70° 31.7' (-46°C)	2.999	Lead
.....	.....	.....	79 (18°C)	.....	Body-centered cubic	3.140	.....	.....	2.720	Lithium
.....	.....	0.00011	.....	.....	Close-packed hexagonal*	3.650	.....	5.890	3.62	Lutecium
(c) 13.3	(c) 7.4	0.22	6.84 (20°C)	30	Face-centered cubic	4.52	.....	(-268°C)	3.20	Magnesium
.....	.....	0.000060	.....	.....	Hexagonal*	4.03	.....	6.59 (-234°C)	.....	Manganese
4.6	2.6	.....	9.5 (20°C)	80	Close-packed hexagonal	2.7298	.....	4.3104	2.670	Mercury
11.8	6.6	0.000059	10.8 (20°C)	17	Cubic*	6.83	.....	(-225°C)	2.745	Molybdenum
125	70	0.17	10.17 (11°C)	.....	Face-centered cubic	3.8824	.....	(-35°C)	.....	Neodymium
.....	.....	.....	.....	.....	Cubic*	7.17	.....	.....	3.20	Neon
8.9	4.9	0.17	9.83 (0°C)	21	Face-centered cubic	3.9158	.....	.....	2.769	Neptunium
.....	.....	.....	.....	.....	(probably) Monoclinic (β = 92°)	7.42	4.29	14.10	3.4	Nickel
83	46	0.24	6.15 (0°C)	.....	Body-centered cubic	5.333	.....	.....	4.618	Nitrogen
.....	.....	.....	88 (18°C)	.....	Close-packed hexagonal*	3.662	.....	5.908	3.633	Osmium
.....	.....	.....	.....	.....	.....	.....	.....	.....	.....	Oxygen
(c) 8.3	(c) 4.6	0.21	4.5 (20°C)	42	Close-packed hexagonal	2.7553	.....	4.4493	2.734	Palladium
90	50	.....	12.5 (20°C)	.....	Face-centered cubic*	3.7957	.....	.....	2.684	Phosphorus (yellow)
9.1	5.1	.....	7.6 (0°C)	60	Body-centered cubic	5.62	.....	(-173°C)	4.87	Platinum
.....	.....	.....	.....	.....	Close-packed hexagonal*	2.6984	.....	4.2730	2.644	Plutonium
37	21	.....	.....	.....	Face-centered cubic*	4.532	.....	.....	3.205	Polonium
2.8 to 7.3	1.6 to 4.1	0.20	10 <sup>5</sup> (0°C)	16	Hexagonal*	4.3552	.....	4.9494	2.32	Potassium
(c) 19.7	(c) 10.9	(m) 1.0	1.59 (20°C)	11	Diamond cubic	5.4173	.....	.....	2.346	Praseodymium
71	39	0.32	4.2 (0°C)	.....	Face-centered cubic	4.0774	.....	.....	2.882	Protoactinium
64	36	6.31 × 10 <sup>-4</sup>	23 (20°C)	.....	Body-centered cubic	4.2820	.....	.....	3.708	Radium
.....	.....	.....	2 × 10 <sup>12</sup> (20°C)	.....	Face-centered cubic*	6.075	.....	.....	4.30	Rhenium
6.5	3.6	0.13	12.4 (18°C)	27	Face-centered orthorhombic*	10.48	12.92	24.55	2.12	Rhodium
.....	.....	.....	.....	.....	Body-centered cubic	3.2959	.....	.....	2.854	Rubidium
16.8	9.3	0.014	2 × 10 <sup>11</sup> (19.6°C)	6	.....	4.4469	.....	5.9149	2.86	Ruthenium
28	16	0.093	18 (0°C)	.....	Close-packed hexagonal	3.585	.....	5.664	3.508	Samarium
(c) 11.1	(c) 6.2	.....	19 (20°C)	.....	Close-packed hexagonal*	3.450	.....	5.514	3.401	Scandium
.....	.....	.....	.....	.....	Face-centered cubic	5.077	.....	.....	3.59	Selenium
23	13	0.18	11.5 (20°C)	6	Close-packed hexagonal	3.523	.....	5.564	3.446	Silicon
8.5	4.7	.....	80 (0°C)	16.8	Body-centered tetragonal*	5.8194	.....	3.1753	3.016	Silver
4.3	2.4	0.48	5.5 (20°C)	50	Close-packed hexagonal*	2.953	.....	4.729	2.91	Sodium
.....	.....	0.064	60 (18°C)	.....	Body-centered cubic*	3.1585	.....	.....	2.734	Strontium
7.8	4.3	.....	26 (20°C)	.....	Orthorhombic*	2.852	5.865	4.945	2.76	Sulfur (yellow)
.....	.....	1.24 × 10 <sup>-4</sup>	.....	.....	Body-centered cubic	3.033	.....	.....	2.627	Tantalum
.....	.....	.....	.....	.....	Face-centered cubic	6.24	.....	(-185°C)	4.41	Tellurium
.....	.....	.....	.....	.....	Face-centered cubic	5.468	.....	.....	3.866	Technetium
.....	.....	.....	.....	.....	Close-packed hexagonal	3.663	.....	5.814	3.59	Terbium
(c) 29.7	22.1	0.27	(c) 5.916 (20°C)	(t)	Close-packed hexagonal	2.659	.....	4.935	2.659	Thallium
5	3	.....	41.0 (0°C)	11	Close-packed hexagonal*	3.223	.....	5.123	3.16	Thorium

(For footnotes, see page 19.)